

Abstract

- 5 Organopolysiloxane compositions that cure by the addition reaction of  
silicon-bonded lower alkenyl radicals with silicon-bonded hydrogen atoms  
and which exhibit select adhesion to a variety of substrates. The  
compositions comprise an adhesion promoting mixture comprising an  
epoxy-functional compound, soluble polydiorganosiloxanes,  
polycycloorganosiloxanes (linear and cyclic) and and hydroxy end blocked  
10 hydrocarbons (glycols) thus giving release characteristics to metal  
substrates while maintaining adhesion to a thermoplastic substrate.  
Additionally, an additive may be used to produce surface lubricity after  
curing.

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